

ABSTRACT OF THE DISCLOSURE

Disclosed is a turning tool for cutting circumferential grooves into a surface of a polishing pad formed of a resin material and utilized for polishing semiconductor devices. The turning tool comprising a cutting part arranged to have a tooth width within a range of 0.005-1.0mm, a wedge angle within a range of 15-35 degrees, and a front clearance angle within a range of 65-45 degrees. A polishing pad effectively formed by using the turning tool, and an apparatus and a method of producing such a polishing pad by utilizing the turning tool are also disclosed.

TELETYPE RECORD